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### Understanding [Embedded - CPLDs \(Complex Programmable Logic Devices\)](#)

Embedded - CPLDs, or Complex Programmable Logic Devices, are highly versatile digital logic devices used in electronic systems. These programmable components are designed to perform complex logical operations and can be customized for specific applications. Unlike fixed-function ICs, CPLDs offer the flexibility to reprogram their configuration, making them an ideal choice for various embedded systems. They consist of a set of logic gates and programmable interconnects, allowing designers to implement complex logic circuits without needing custom hardware.

### Applications of Embedded - CPLDs

#### Details

Product Status	Obsolete
Programmable Type	In System Programmable
Delay Time tpd(1) Max	5 ns
Voltage Supply - Internal	3V ~ 3.6V
Number of Logic Elements/Blocks	8
Number of Macrocells	128
Number of Gates	2500
Number of I/O	100
Operating Temperature	0°C ~ 70°C (TA)
Mounting Type	Surface Mount
Package / Case	144-LQFP
Supplier Device Package	144-TQFP (20x20)
Purchase URL	<a href="https://www.e-xfl.com/product-detail/intel/epm7128aetc144-5n">https://www.e-xfl.com/product-detail/intel/epm7128aetc144-5n</a>

**Table 1. MAX 7000A Device Features**

Feature	EPM7032AE	EPM7064AE	EPM7128AE	EPM7256AE	EPM7512AE
Usable gates	600	1,250	2,500	5,000	10,000
Macrocells	32	64	128	256	512
Logic array blocks	2	4	8	16	32
Maximum user I/O pins	36	68	100	164	212
$t_{PD}$ (ns)	4.5	4.5	5.0	5.5	7.5
$t_{SU}$ (ns)	2.9	2.8	3.3	3.9	5.6
$t_{FSU}$ (ns)	2.5	2.5	2.5	2.5	3.0
$t_{CO1}$ (ns)	3.0	3.1	3.4	3.5	4.7
$f_{CNT}$ (MHz)	227.3	222.2	192.3	172.4	116.3

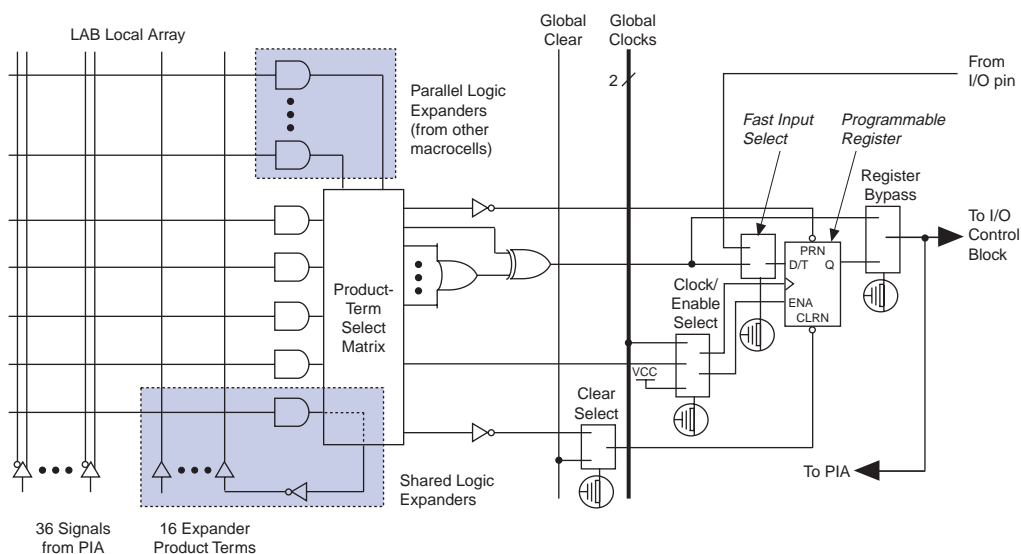
## ...and More Features

- 4.5-ns pin-to-pin logic delays with counter frequencies of up to 227.3 MHz
- MultiVolt™ I/O interface enables device core to run at 3.3 V, while I/O pins are compatible with 5.0-V, 3.3-V, and 2.5-V logic levels
- Pin counts ranging from 44 to 256 in a variety of thin quad flat pack (TQFP), plastic quad flat pack (PQFP), ball-grid array (BGA), space-saving FineLine BGA™, and plastic J-lead chip carrier (PLCC) packages
- Supports hot-socketing in MAX 7000AE devices
- Programmable interconnect array (PIA) continuous routing structure for fast, predictable performance
- PCI-compatible
- Bus-friendly architecture, including programmable slew-rate control
- Open-drain output option
- Programmable macrocell registers with individual clear, preset, clock, and clock enable controls
- Programmable power-up states for macrocell registers in MAX 7000AE devices
- Programmable power-saving mode for 50% or greater power reduction in each macrocell
- Configurable expander product-term distribution, allowing up to 32 product terms per macrocell
- Programmable security bit for protection of proprietary designs
- 6 to 10 pin- or logic-driven output enable signals
- Two global clock signals with optional inversion
- Enhanced interconnect resources for improved routability
- Fast input setup times provided by a dedicated path from I/O pin to macrocell registers
- Programmable output slew-rate control
- Programmable ground pins

## Macrocells

MAX 7000A macrocells can be individually configured for either sequential or combinatorial logic operation. The macrocells consist of three functional blocks: the logic array, the product-term select matrix, and the programmable register. **Figure 2** shows a MAX 7000A macrocell.

**Figure 2. MAX 7000A Macrocell**



Combinatorial logic is implemented in the logic array, which provides five product terms per macrocell. The product-term select matrix allocates these product terms for use as either primary logic inputs (to the OR and XOR gates) to implement combinatorial functions, or as secondary inputs to the macrocell's register preset, clock, and clock enable control functions.

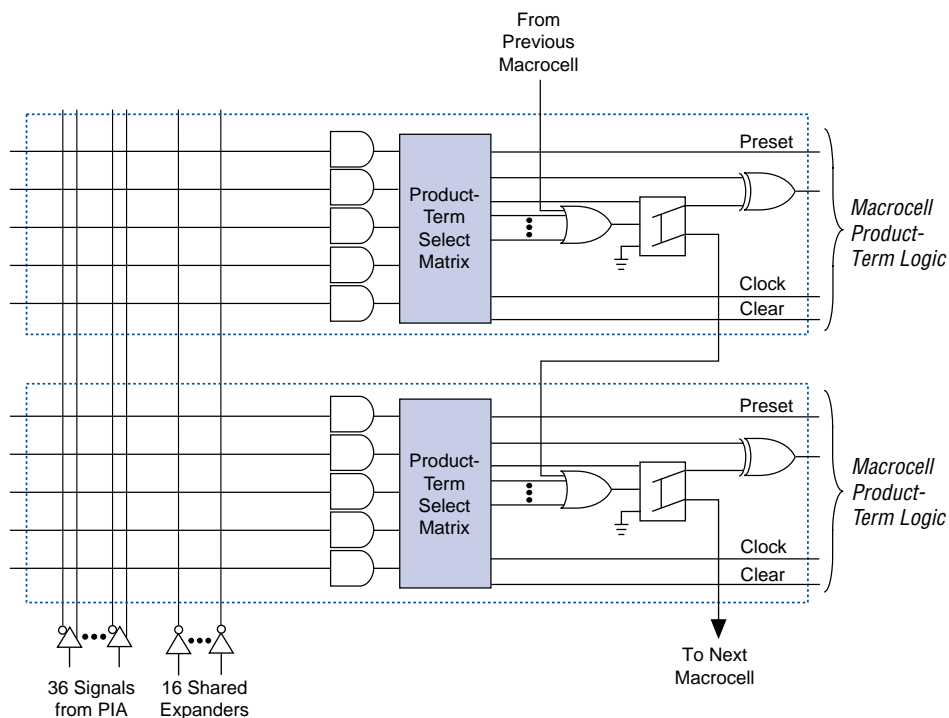
Two kinds of expander product terms ("expanders") are available to supplement macrocell logic resources:

- Shareable expanders, which are inverted product terms that are fed back into the logic array
- Parallel expanders, which are product terms borrowed from adjacent macrocells

The Altera development system automatically optimizes product-term allocation according to the logic requirements of the design.

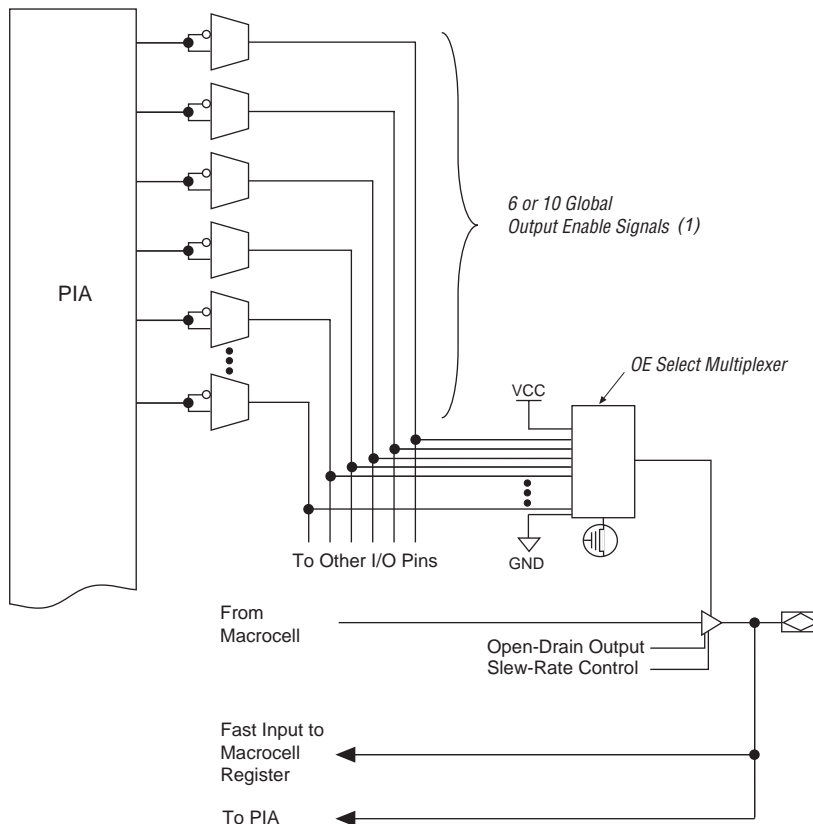
**Figure 4. MAX 7000A Parallel Expanders**

*Unused product terms in a macrocell can be allocated to a neighboring macrocell.*



## Programmable Interconnect Array

Logic is routed between LABs on the PIA. This global bus is a programmable path that connects any signal source to any destination on the device. All MAX 7000A dedicated inputs, I/O pins, and macrocell outputs feed the PIA, which makes the signals available throughout the entire device. Only the signals required by each LAB are actually routed from the PIA into the LAB. Figure 5 shows how the PIA signals are routed into the LAB. An EEPROM cell controls one input to a 2-input AND gate, which selects a PIA signal to drive into the LAB.

**Figure 6. I/O Control Block of MAX 7000A Devices****Note:**

- (1) EPM7032AE, EPM7064AE, EPM7128A, EPM7128AE, EPM7256A, and EPM7256AE devices have six output enable signals. EPM7512AE devices have 10 output enable signals.

When the tri-state buffer control is connected to ground, the output is tri-stated (high impedance) and the I/O pin can be used as a dedicated input. When the tri-state buffer control is connected to  $V_{CC}$ , the output is enabled.

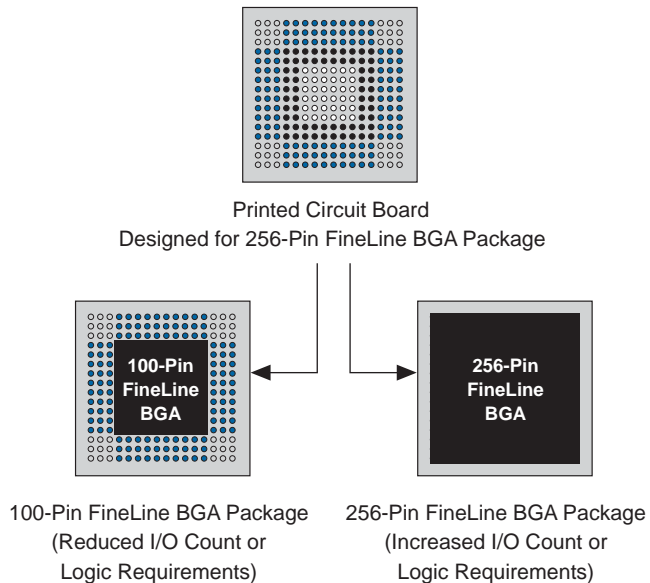
The MAX 7000A architecture provides dual I/O feedback, in which macrocell and pin feedbacks are independent. When an I/O pin is configured as an input, the associated macrocell can be used for buried logic.

## SameFrame Pin-Outs

MAX 7000A devices support the SameFrame pin-out feature for FineLine BGA packages. The SameFrame pin-out feature is the arrangement of balls on FineLine BGA packages such that the lower-ball-count packages form a subset of the higher-ball-count packages. SameFrame pin-outs provide the flexibility to migrate not only from device to device within the same package, but also from one package to another. A given printed circuit board (PCB) layout can support multiple device density/package combinations. For example, a single board layout can support a range of devices from an EPM7128AE device in a 100-pin FineLine BGA package to an EPM7512AE device in a 256-pin FineLine BGA package.

The Altera design software provides support to design PCBs with SameFrame pin-out devices. Devices can be defined for present and future use. The software generates pin-outs describing how to lay out a board to take advantage of this migration (see [Figure 7](#)).

**Figure 7. SameFrame Pin-Out Example**



## In-System Programmability

MAX 7000A devices can be programmed in-system via an industry-standard 4-pin IEEE Std. 1149.1 (JTAG) interface. ISP offers quick, efficient iterations during design development and debugging cycles. The MAX 7000A architecture internally generates the high programming voltages required to program EEPROM cells, allowing in-system programming with only a single 3.3-V power supply. During in-system programming, the I/O pins are tri-stated and weakly pulled-up to eliminate board conflicts. The pull-up value is nominally 50 k $\Omega$ .

MAX 7000AE devices have an enhanced ISP algorithm for faster programming. These devices also offer an ISP\_Done bit that provides safe operation when in-system programming is interrupted. This ISP\_Done bit, which is the last bit programmed, prevents all I/O pins from driving until the bit is programmed. This feature is only available in EPM7032AE, EPM7064AE, EPM7128AE, EPM7256AE, and EPM7512AE devices.

ISP simplifies the manufacturing flow by allowing devices to be mounted on a PCB with standard pick-and-place equipment before they are programmed. MAX 7000A devices can be programmed by downloading the information via in-circuit testers, embedded processors, the Altera MasterBlaster serial/USB communications cable, ByteBlasterMV parallel port download cable, and BitBlaster serial download cable. Programming the devices after they are placed on the board eliminates lead damage on high-pin-count packages (e.g., QFP packages) due to device handling. MAX 7000A devices can be reprogrammed after a system has already shipped to the field. For example, product upgrades can be performed in the field via software or modem.

In-system programming can be accomplished with either an adaptive or constant algorithm. An adaptive algorithm reads information from the unit and adapts subsequent programming steps to achieve the fastest possible programming time for that unit. A constant algorithm uses a pre-defined (non-adaptive) programming sequence that does not take advantage of adaptive algorithm programming time improvements. Some in-circuit testers cannot program using an adaptive algorithm. Therefore, a constant algorithm must be used. MAX 7000AE devices can be programmed with either an adaptive or constant (non-adaptive) algorithm. EPM7128A and EPM7256A device can only be programmed with an adaptive algorithm; users programming these two devices on platforms that cannot use an adaptive algorithm should use EPM7128AE and EPM7256AE devices.

The Jam Standard Test and Programming Language (STAPL), JEDEC standard JESD 71, can be used to program MAX 7000A devices with in-circuit testers, PCs, or embedded processors.

## Programming Times

The time required to implement each of the six programming stages can be broken into the following two elements:

- A pulse time to erase, program, or read the EEPROM cells.
- A shifting time based on the test clock (TCK) frequency and the number of TCK cycles to shift instructions, address, and data into the device.

By combining the pulse and shift times for each of the programming stages, the program or verify time can be derived as a function of the TCK frequency, the number of devices, and specific target device(s). Because different ISP-capable devices have a different number of EEPROM cells, both the total fixed and total variable times are unique for a single device.

### *Programming a Single MAX 7000A Device*

The time required to program a single MAX 7000A device in-system can be calculated from the following formula:

$$t_{PROG} = t_{PPULSE} + \frac{Cycle_{PTCK}}{f_{TCK}}$$

where:  $t_{PROG}$  = Programming time  
 $t_{PPULSE}$  = Sum of the fixed times to erase, program, and verify the EEPROM cells  
 $Cycle_{PTCK}$  = Number of TCK cycles to program a device  
 $f_{TCK}$  = TCK frequency

The ISP times for a stand-alone verification of a single MAX 7000A device can be calculated from the following formula:

$$t_{VER} = t_{VPULSE} + \frac{Cycle_{VTCK}}{f_{TCK}}$$

where:  $t_{VER}$  = Verify time  
 $t_{VPULSE}$  = Sum of the fixed times to verify the EEPROM cells  
 $Cycle_{VTCK}$  = Number of TCK cycles to verify a device



**Table 19. EPM7064AE External Timing Parameters** *Note (1)*

Symbol	Parameter	Conditions	Speed Grade						Unit
			-4		-7		-10		
			Min	Max	Min	Max	Min	Max	
t <sub>PD1</sub>	Input to non-registered output	C1 = 35 pF (2)		4.5		7.5		10.0	ns
t <sub>PD2</sub>	I/O input to non-registered output	C1 = 35 pF (2)		4.5		7.5		10.0	ns
t <sub>SU</sub>	Global clock setup time	(2)	2.8		4.7		6.2		ns
t <sub>H</sub>	Global clock hold time	(2)	0.0		0.0		0.0		ns
t <sub>FSU</sub>	Global clock setup time of fast input		2.5		3.0		3.0		ns
t <sub>FH</sub>	Global clock hold time of fast input		0.0		0.0		0.0		ns
t <sub>CO1</sub>	Global clock to output delay	C1 = 35 pF	1.0	3.1	1.0	5.1	1.0	7.0	ns
t <sub>CH</sub>	Global clock high time		2.0		3.0		4.0		ns
t <sub>CL</sub>	Global clock low time		2.0		3.0		4.0		ns
t <sub>ASU</sub>	Array clock setup time	(2)	1.6		2.6		3.6		ns
t <sub>AH</sub>	Array clock hold time	(2)	0.3		0.4		0.6		ns
t <sub>ACO1</sub>	Array clock to output delay	C1 = 35 pF (2)	1.0	4.3	1.0	7.2	1.0	9.6	ns
t <sub>ACH</sub>	Array clock high time		2.0		3.0		4.0		ns
t <sub>ACL</sub>	Array clock low time		2.0		3.0		4.0		ns
t <sub>CPPW</sub>	Minimum pulse width for clear and preset	(3)	2.0		3.0		4.0		ns
t <sub>CNT</sub>	Minimum global clock period	(2)		4.5		7.4		10.0	ns
f <sub>CNT</sub>	Maximum internal global clock frequency	(2), (4)	222.2		135.1		100.0		MHz
t <sub>ACNT</sub>	Minimum array clock period	(2)		4.5		7.4		10.0	ns
f <sub>ACNT</sub>	Maximum internal array clock frequency	(2), (4)	222.2		135.1		100.0		MHz

**Table 20. EPM7064AE Internal Timing Parameters (Part 2 of 2)** *Note (1)*

Symbol	Parameter	Conditions	Speed Grade						Unit
			-4		-7		-10		
			Min	Max	Min	Max	Min	Max	
$t_{EN}$	Register enable time			0.6		1.0		1.2	ns
$t_{GLOB}$	Global control delay			1.0		1.5		2.2	ns
$t_{PRE}$	Register preset time			1.3		2.1		2.9	ns
$t_{CLR}$	Register clear time			1.3		2.1		2.9	ns
$t_{PIA}$	PIA delay	(2)		1.0		1.7		2.3	ns
$t_{LPA}$	Low-power adder	(6)		3.5		4.0		5.0	ns

**Table 21. EPM7128AE External Timing Parameters** *Note (1)*

Symbol	Parameter	Conditions	Speed Grade						Unit
			-5		-7		-10		
			Min	Max	Min	Max	Min	Max	
t <sub>PD1</sub>	Input to non-registered output	C1 = 35 pF (2)		5.0		7.5		10	ns
t <sub>PD2</sub>	I/O input to non-registered output	C1 = 35 pF (2)		5.0		7.5		10	ns
t <sub>SU</sub>	Global clock setup time	(2)	3.3		4.9		6.6		ns
t <sub>H</sub>	Global clock hold time	(2)	0.0		0.0		0.0		ns
t <sub>FSU</sub>	Global clock setup time of fast input		2.5		3.0		3.0		ns
t <sub>FH</sub>	Global clock hold time of fast input		0.0		0.0		0.0		ns
t <sub>CO1</sub>	Global clock to output delay	C1 = 35 pF	1.0	3.4	1.0	5.0	1.0	6.6	ns
t <sub>CH</sub>	Global clock high time		2.0		3.0		4.0		ns
t <sub>CL</sub>	Global clock low time		2.0		3.0		4.0		ns
t <sub>ASU</sub>	Array clock setup time	(2)	1.8		2.8		3.8		ns
t <sub>AH</sub>	Array clock hold time	(2)	0.2		0.3		0.4		ns
t <sub>ACO1</sub>	Array clock to output delay	C1 = 35 pF (2)	1.0	4.9	1.0	7.1	1.0	9.4	ns
t <sub>ACH</sub>	Array clock high time		2.0		3.0		4.0		ns
t <sub>ACL</sub>	Array clock low time		2.0		3.0		4.0		ns
t <sub>CPPW</sub>	Minimum pulse width for clear and preset	(3)	2.0		3.0		4.0		ns
t <sub>CNT</sub>	Minimum global clock period	(2)		5.2		7.7		10.2	ns
f <sub>CNT</sub>	Maximum internal global clock frequency	(2), (4)	192.3		129.9		98.0		MHz
t <sub>ACNT</sub>	Minimum array clock period	(2)		5.2		7.7		10.2	ns
f <sub>ACNT</sub>	Maximum internal array clock frequency	(2), (4)	192.3		129.9		98.0		MHz

**Table 22. EPM7128AE Internal Timing Parameters (Part 2 of 2)** *Note (1)*

Symbol	Parameter	Conditions	Speed Grade						Unit
			-5		-7		-10		
			Min	Max	Min	Max	Min	Max	
$t_{EN}$	Register enable time			0.7		1.0		1.3	ns
$t_{GLOB}$	Global control delay			1.1		1.6		2.0	ns
$t_{PRE}$	Register preset time			1.4		2.0		2.7	ns
$t_{CLR}$	Register clear time			1.4		2.0		2.7	ns
$t_{PIA}$	PIA delay	(2)		1.4		2.0		2.6	ns
$t_{LPA}$	Low-power adder	(6)		4.0		4.0		5.0	ns

**Table 25. EPM7512AE External Timing Parameters** *Note (1)*

Symbol	Parameter	Conditions	Speed Grade						Unit
			-7		-10		-12		
			Min	Max	Min	Max	Min	Max	
t <sub>PD1</sub>	Input to non-registered output	C1 = 35 pF (2)		7.5		10.0		12.0	ns
t <sub>PD2</sub>	I/O input to non-registered output	C1 = 35 pF (2)		7.5		10.0		12.0	ns
t <sub>SU</sub>	Global clock setup time	(2)	5.6		7.6		9.1		ns
t <sub>H</sub>	Global clock hold time	(2)	0.0		0.0		0.0		ns
t <sub>FSU</sub>	Global clock setup time of fast input		3.0		3.0		3.0		ns
t <sub>FH</sub>	Global clock hold time of fast input		0.0		0.0		0.0		ns
t <sub>CO1</sub>	Global clock to output delay	C1 = 35 pF	1.0	4.7	1.0	6.3	1.0	7.5	ns
t <sub>CH</sub>	Global clock high time		3.0		4.0		5.0		ns
t <sub>CL</sub>	Global clock low time		3.0		4.0		5.0		ns
t <sub>ASU</sub>	Array clock setup time	(2)	2.5		3.5		4.1		ns
t <sub>AH</sub>	Array clock hold time	(2)	0.2		0.3		0.4		ns
t <sub>ACO1</sub>	Array clock to output delay	C1 = 35 pF (2)	1.0	7.8	1.0	10.4	1.0	12.5	ns
t <sub>ACH</sub>	Array clock high time		3.0		4.0		5.0		ns
t <sub>ACL</sub>	Array clock low time		3.0		4.0		5.0		ns
t <sub>CPPW</sub>	Minimum pulse width for clear and preset	(3)	3.0		4.0		5.0		ns
t <sub>CNT</sub>	Minimum global clock period	(2)		8.6		11.5		13.9	ns
f <sub>CNT</sub>	Maximum internal global clock frequency	(2), (4)	116.3		87.0		71.9		MHz
t <sub>ACNT</sub>	Minimum array clock period	(2)		8.6		11.5		13.9	ns
f <sub>ACNT</sub>	Maximum internal array clock frequency	(2), (4)	116.3		87.0		71.9		MHz

**Table 26. EPM7512AE Internal Timing Parameters (Part 2 of 2)** *Note (1)*

Symbol	Parameter	Conditions	Speed Grade						Unit
			-7		-10		-12		
			Min	Max	Min	Max	Min	Max	
$t_{IC}$	Array clock delay			1.8		2.3		2.9	ns
$t_{EN}$	Register enable time			1.0		1.3		1.7	ns
$t_{GLOB}$	Global control delay			1.7		2.2		2.7	ns
$t_{PRE}$	Register preset time			1.0		1.4		1.7	ns
$t_{CLR}$	Register clear time			1.0		1.4		1.7	ns
$t_{PIA}$	PIA delay	(2)		3.0		4.0		4.8	ns
$t_{LPA}$	Low-power adder	(6)		4.5		5.0		5.0	ns

Table 27. EPM7128A External Timing Parameters

Note (1)

Symbol	Parameter	Conditions	Speed Grade								Unit
			-6		-7		-10		-12		
			Min	Max	Min	Max	Min	Max	Min	Max	
t <sub>PD1</sub>	Input to non-registered output	C1 = 35 pF (2)		6.0		7.5		10.0		12.0	ns
t <sub>PD2</sub>	I/O input to non-registered output	C1 = 35 pF (2)		6.0		7.5		10.0		12.0	ns
t <sub>SU</sub>	Global clock setup time	(2)	4.2		5.3		7.0		8.5		ns
t <sub>H</sub>	Global clock hold time	(2)	0.0		0.0		0.0		0.0		ns
t <sub>FSU</sub>	Global clock setup time of fast input		2.5		3.0		3.0		3.0		ns
t <sub>FH</sub>	Global clock hold time of fast input		0.0		0.0		0.0		0.0		ns
t <sub>CO1</sub>	Global clock to output delay	C1 = 35 pF	1.0	3.7	1.0	4.6	1.0	6.1	1.0	7.3	ns
t <sub>CH</sub>	Global clock high time		3.0		3.0		4.0		5.0		ns
t <sub>CL</sub>	Global clock low time		3.0		3.0		4.0		5.0		ns
t <sub>ASU</sub>	Array clock setup time	(2)	1.9		2.4		3.1		3.8		ns
t <sub>AH</sub>	Array clock hold time	(2)	1.5		2.2		3.3		4.3		ns
t <sub>ACO1</sub>	Array clock to output delay	C1 = 35 pF (2)	1.0	6.0	1.0	7.5	1.0	10.0	1.0	12.0	ns
t <sub>ACH</sub>	Array clock high time		3.0		3.0		4.0		5.0		ns
t <sub>ACL</sub>	Array clock low time		3.0		3.0		4.0		5.0		ns
t <sub>CPPW</sub>	Minimum pulse width for clear and preset	(3)	3.0		3.0		4.0		5.0		ns
t <sub>CNT</sub>	Minimum global clock period	(2)		6.9		8.6		11.5		13.8	ns
f <sub>CNT</sub>	Maximum internal global clock frequency	(2), (4)	144.9		116.3		87.0		72.5		MHz
t <sub>ACNT</sub>	Minimum array clock period	(2)		6.9		8.6		11.5		13.8	ns
f <sub>ACNT</sub>	Maximum internal array clock frequency	(2), (4)	144.9		116.3		87		72.5		MHz

**Table 28. EPM7128A Internal Timing Parameters (Part 2 of 2)** *Note (1)*

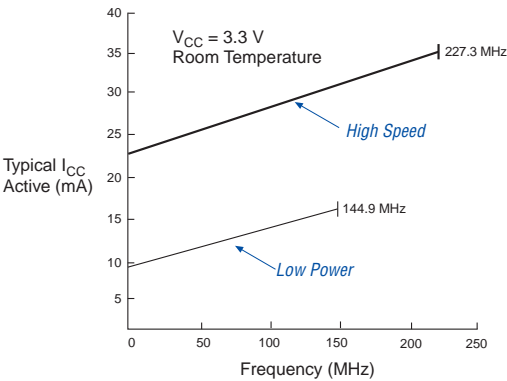
Symbol	Parameter	Conditions	Speed Grade								Unit
			-6		-7		-10		-12		
			Min	Max	Min	Max	Min	Max	Min	Max	
$t_{RD}$	Register delay			1.7		2.1		2.8		3.3	ns
$t_{COMB}$	Combinatorial delay			1.7		2.1		2.8		3.3	ns
$t_{IC}$	Array clock delay			2.4		3.0		4.1		4.9	ns
$t_{EN}$	Register enable time			2.4		3.0		4.1		4.9	ns
$t_{GLOB}$	Global control delay			1.0		1.2		1.7		2.0	ns
$t_{PRE}$	Register preset time			3.1		3.9		5.2		6.2	ns
$t_{CLR}$	Register clear time			3.1		3.9		5.2		6.2	ns
$t_{PIA}$	PIA delay	(2)		0.9		1.1		1.5		1.8	ns
$t_{LPA}$	Low-power adder	(6)		11.0		10.0		10.0		10.0	ns



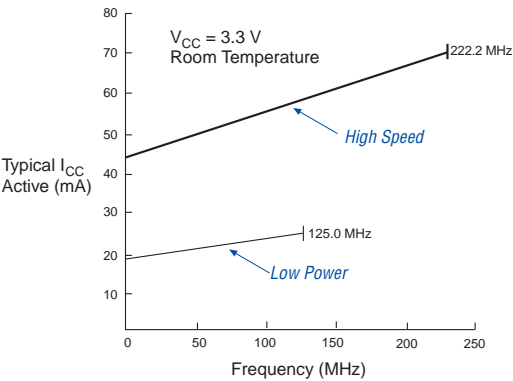
Figure 13 shows the typical supply current versus frequency for MAX 7000A devices.

Figure 13.  $I_{CC}$  vs. Frequency for MAX 7000A Devices (Part 1 of 2)

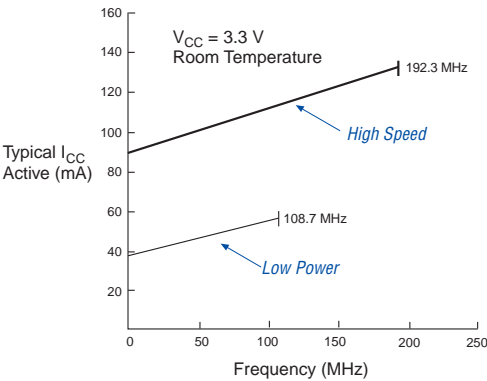
EPM7032AE

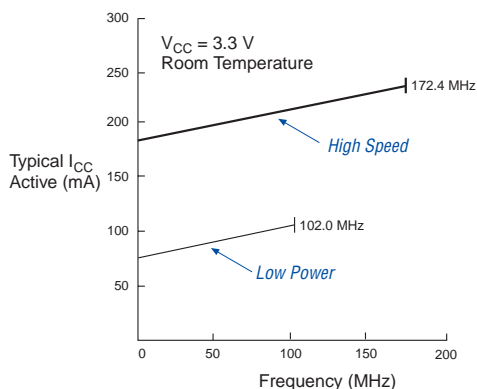
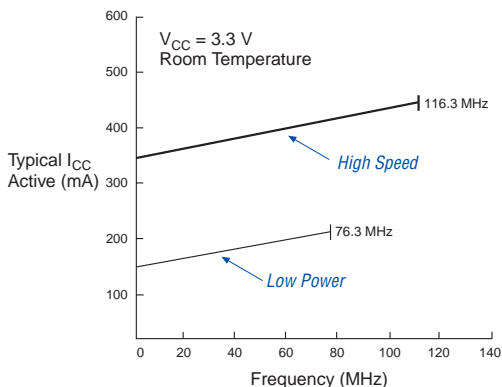


EPM7064AE



EPM7128A & EPM7128AE



**Figure 13.  $I_{CC}$  vs. Frequency for MAX 7000A Devices (Part 2 of 2)****EPM7256A & EPM7256AE****EPM7512AE**

## Device Pin-Outs

See the Altera web site (<http://www.altera.com>) or the *Altera Digital Library* for pin-out information.

Figures 14 through 23 show the package pin-out diagrams for MAX 7000A devices.

**Figure 14. 44-Pin PLCC/TQFP Package Pin-Out Diagram**

Package outlines not drawn to scale.

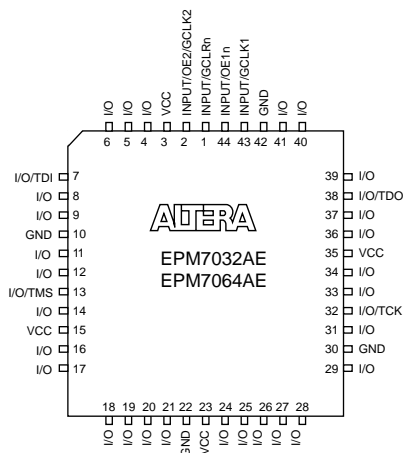
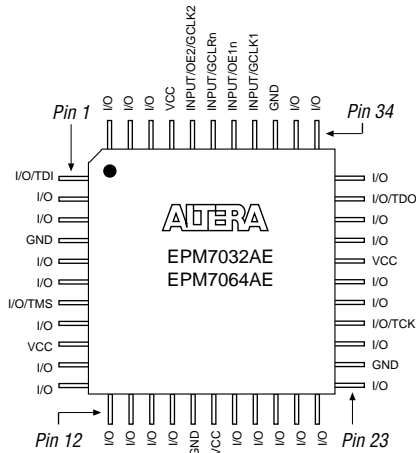
**44-Pin PLCC****44-Pin TQFP**

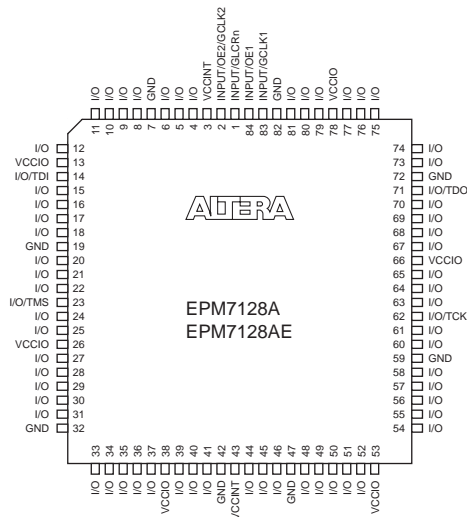
Figure 15. 49-Pin Ultra FineLine BGA Package Pin-Out Diagram

Package outlines not drawn to scale.



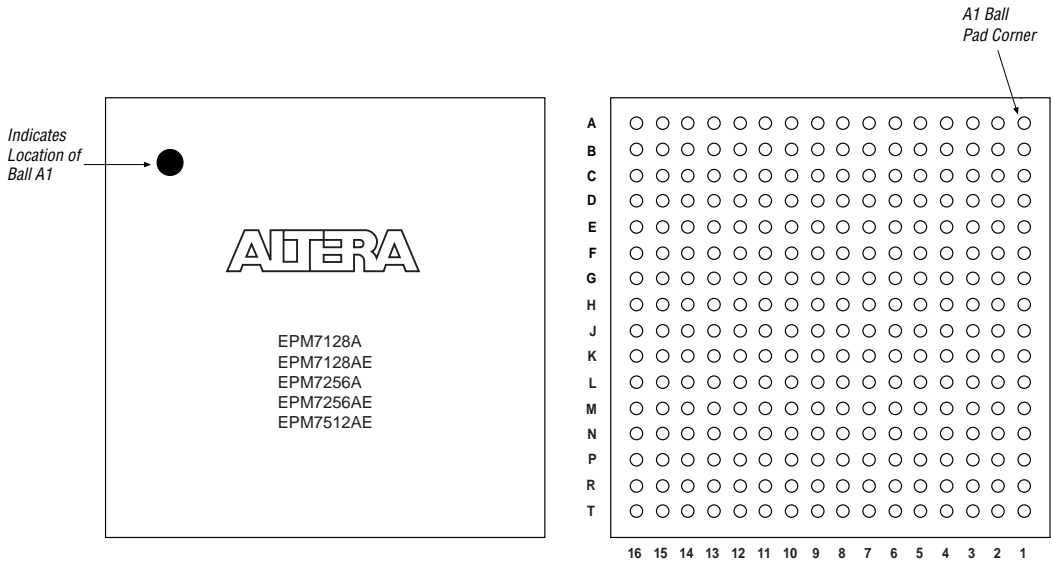
Figure 16. 84-Pin PLCC Package Pin-Out Diagram

Package outline not drawn to scale.



**Figure 23. 256-Pin FineLine BGA Package Pin-Out Diagram**

Package outline not drawn to scale.



## Revision History

The information contained in the *MAX 7000A Programmable Logic Device Data Sheet* version 4.5 supersedes information published in previous versions.

### Version 4.5

The following changes were made in the *MAX 7000A Programmable Logic Device Data Sheet* version 4.5:

- Updated text in the “Power Sequencing & Hot-Socketing” section.

### Version 4.4

The following changes were made in the *MAX 7000A Programmable Logic Device Data Sheet* version 4.4:

- Added Tables 5 through 7.
- Added “Programming Sequence” on page 17 and “Programming Times” on page 18.

## Version 4.3

The following changes were made in the *MAX 7000A Programmable Logic Device Data Sheet* version 4.3:

- Added extended temperature devices to document
- Updated [Table 14](#).

## Version 4.2

The following changes were made in the *MAX 7000A Programmable Logic Device Data Sheet* version 4.2:

- Removed *Note (1)* from [Table 2](#).
- Removed *Note (4)* from [Tables 3](#) and [4](#).

## Version 4.1

The following changes were made in the *MAX 7000A Programmable Logic Device Data Sheet* version 4.1:

- Updated leakage current information in [Table 15](#).
- Updated [Note \(9\)](#) of [Table 15](#).
- Updated [Note \(1\)](#) of [Tables 17](#) through [30](#).



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